PRODUCT NO.

10033854-*52**

PIN NO.2 — LOT NO. — PIN NO.200

FCI
YYMMDD
R 1.8V
−A−
0.9±0.05
PIN NO.1
PIN NO.199

70.86

P.C.B OUT LINE
69.4
72.2 LATCH MOVE AREA

25.2
5.2

X
X

30°
3.3
1   1
4.4   4.4

SECT X−X

3.25
63.6±0.2
4.35 TYP.(2)

14.1
48.9

2.7   1.5
⊕ A 0.2
0.2

3.6

15±0.1 TYP.(2)

3

⊕ A 0.2
ø1.45 +0 −0.1 (LOCATING PEG)

2.4   1.8
13.8   49.2
66.8

⊕ A 0.2
ø0.95 +0 −0.1 (LOCATING PEG)

0.6

NOTE
  1. PRODUCT SPEC. : GS−12−195
  2. PACKAGING SPEC. : GS−14−786
  3. MATERIAL
    1) HOUSING : LCP, UL94V−0, COLOR BLACK
    2) CONTACT : COPPER ALLOY
    3) HOLD DOWN : BRASS
  4. FINISH
    1) TERMINAL : SEE TABLE
    2) HOLD DOWN : SEE TABLE
  5. CO−PLANARITY : 0.1 MAX.(INCLUDE HOLD DOWN)
  6. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY
     REGULATIONS AS DESCRIBED IN GS−22−008.
  7. THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK
     TEMPERATURE FOR 10 SECONDS IN A REFLOW SOLDER APPLICATION.

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY			FCI www.fciconnect.com
ltr	ecn no	dr	date	.X ± 0.20		projection		title	
2		M H	8/28/'03	linear	.XX ± 0.10			DDR II 0.6 mm PITCH 200 POS. REVERSE TYPE ASS'Y	
3		M H	4/2/'04						
4		M H	6/29/'04	angles	0° ±5°				
A	J04−0401	M H	9/28/'04	dr	M.Hasegawa 6/29/'04	MM		product family 50UF SO−DIMM	code
B	T05−0022	R C	11/9/'04	engr	M.Hasegawa 6/29/'04			size dwg no	JP
C	T05−0229	R C	10/12/'05	chr		scale		B 10033854	sheet
D	DG08−0333	B L	12/1/'08	appd		2:1			1 of 4
sheet	revision	D	D	D	D				
index	sheet		1	2	3	4			

ACAD

PDM: Rev:D   STATUS:Released   Printed: Mar 20, 2010

PRODUCT NO.

10033854-*52**

66.8±0.08
63±0.03
2.05±0.03
11.4±0.03
47.4±0.03
1.75±0.03
0.6±0.03
4.2±0.03
0.35±0.03
2±0.02
PIN NO.2
ø1.6±0.1 (HOLE)
PIN NO.200
ø1.1±0.1 (HOLE)
3.1±0.05
3.1±0.05
12±0.05
PIN NO.1
PIN NO.199
2±0.02
4.6±0.1
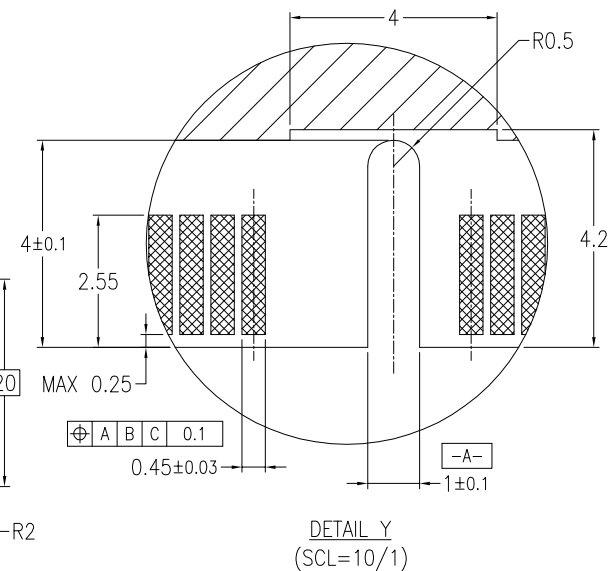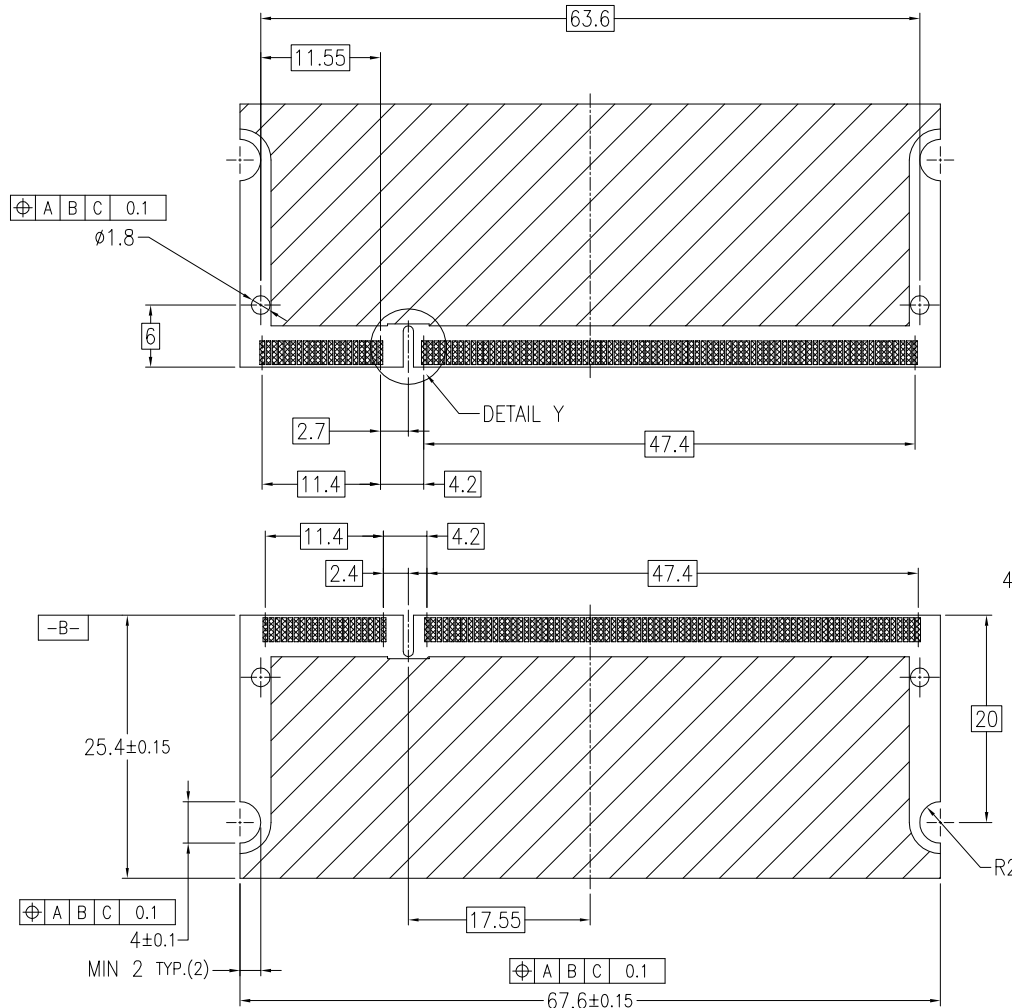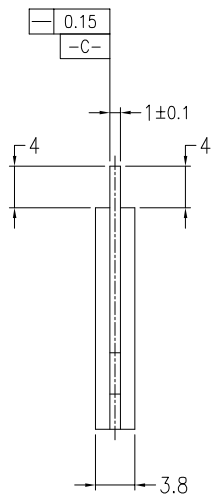4.2±0.03
2.05±0.03
11.4±0.03
47.4±0.03
63±0.03
4.5±0.03
60.6±0.03
3.1±0.03

RECOMMENDED MOUNTING P.C.B LAYOUT

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		title		
ltr	ecn no	dr	date	linear	.X ± 0.20			DDR II 0.6 mm PITCH 200 POS. REVERSE TYPE ASS'Y		
D					.XX ± 0.10	projection				
				angles	0° ±5°			product family 50UF SO-DIMM		code
				dr	M.Hasegawa	6/29/'04	MM			JP
				engr	M.Hasegawa	6/29/'04		size	dwg no	
				chr			scale	B	10033854	sheet
				appd			2:1			2 of
sheet index	revision sheet									

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PRODUCT NO.

10033854-*52**

63.6

11.55

⊕ A B C 0.1
ø1.8

6

2.7

DETAIL Y

11.4 | 4.2

47.4

— 0.15
−C−

1±0.1

4 | 4

3.8

11.4 | 4.2
2.4

47.4

−B−

25.4±0.15

20

−A−

MAX 0.25

⊕ A B C 0.1
0.45±0.03

⊕ A B C 0.1
4±0.1

MIN 2 TYP.(2)

17.55

⊕ A B C 0.1

67.6±0.15

R2

4

R0.5

4±0.1

2.55

4.2

1±0.1

DETAIL Y
(SCL=10/1)

RECOMMENDED MODULE P.C.B LAYOUT

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		title DDR II 0.6 mm PITCH 200 POS. REVERSE TYPE ASS'Y		
ltr	ecn no	dr	date	linear	.X ± 0.20	projection				
D					.XX ± 0.10					
				angles	0° ±5°			product family 50UF SO-DIMM		code JP
				dr	M.Hasegawa	6/29/'04	MM	size	dwg no	
				engr	M.Hasegawa	6/29/'04		B	10033854	sheet 3 of
				chr			scale 2:1			
				appd						
sheet index	revision sheet							www.fciconnect.com		

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PRODUCT NO.	LOCATING PEG	TERMINAL CONTACT AREA FINISH	HOLD DOWN FINISH	SOLDER TAIL FINISH
10033854-052FSLF	YES	Au FLASH	PURE Sn PLATING	Au FLASH
10033854-152FSLF	NO	Au FLASH	PURE Sn PLATING	Au FLASH
10033854-052TSLF	YES	Au 0.3um MIN.	PURE Sn PLATING	Au FLASH
10033854-152TSLF	NO	Au 0.3um MIN.	PURE Sn PLATING	Au FLASH
10033854-052ASLF	YES	Au 0.76um MIN.	PURE Sn PLATING	Au FLASH
10033854-152ASLF	NO	Au 0.76um MIN.	PURE Sn PLATING	Au FLASH
10033854-052FB	YES	Au FLASH	Sn-Pb PLATING	Au FLASH
10033854-152FB	NO	Au FLASH	Sn-Pb PLATING	Au FLASH
10033854-052TB	YES	Au 0.3um MIN.	Sn-Pb PLATING	Au FLASH
10033854-152TB	NO	Au 0.3um MIN.	Sn-Pb PLATING	Au FLASH
10033854-052AB	YES	Au 0.76um MIN.	Sn-Pb PLATING	Au FLASH
10033853-152AB	NO	Au 0.76um MIN.	Sn-Pb PLATING	Au FLASH
10033854-252FSLF	YES	Au FLASH	PURE Sn PLATING	Pure Sn PLATING
10033854-352FSLF	NO	Au FLASH	PURE Sn PLATING	Pure Sn PLATING
10033854-252TSLF	YES	Au 0.3um MIN.	PURE Sn PLATING	Pure Sn PLATING
10033854-352TSLF	NO	Au 0.3um MIN.	PURE Sn PLATING	Pure Sn PLATING
10033854-252ASLF	YES	Au 0.76um MIN.	PURE Sn PLATING	Pure Sn PLATING
10033854-352ASLF	NO	Au 0.76um MIN.	PURE Sn PLATING	Pure Sn PLATING
10033854-252FB	YES	Au FLASH	Sn-Pb PLATING	Pure Sn PLATING
10033854-352FB	NO	Au FLASH	Sn-Pb PLATING	Pure Sn PLATING
10033854-252TB	YES	Au 0.3um MIN.	Sn-Pb PLATING	Pure Sn PLATING
10033854-352TB	NO	Au 0.3um MIN.	Sn-Pb PLATING	Pure Sn PLATING
10033854-252AB	YES	Au 0.76um MIN.	Sn-Pb PLATING	Pure Sn PLATING
10033854-352AB	NO	Au 0.76um MIN.	Sn-Pb PLATING	Pure Sn PLATING
10033854-452FS	YES	Au FLASH	PURE Sn PLATING	Sn-Pb PLATING
10033854-552FS	NO	Au FLASH	PURE Sn PLATING	Sn-Pb PLATING
10033854-452TS	YES	Au 0.3um MIN.	PURE Sn PLATING	Sn-Pb PLATING
10033854-552TS	NO	Au 0.3um MIN.	PURE Sn PLATING	Sn-Pb PLATING
10033854-452AS	YES	Au 0.76um MIN.	PURE Sn PLATING	Sn-Pb PLATING
10033854-552AS	NO	Au 0.76um MIN.	PURE Sn PLATING	Sn-Pb PLATING
10033854-452FB	YES	Au FLASH	Sn-Pb PLATING	Sn-Pb PLATING
10033854-552FB	NO	Au FLASH	Sn-Pb PLATING	Sn-Pb PLATING
10033854-452TB	YES	Au 0.3um MIN.	Sn-Pb PLATING	Sn-Pb PLATING
10033854-552TB	NO	Au 0.3um MIN.	Sn-Pb PLATING	Sn-Pb PLATING
10033854-452AB	YES	Au 0.76um MIN.	Sn-Pb PLATING	Sn-Pb PLATING
10033854-552AB	NO	Au 0.76um MIN.	Sn-Pb PLATING	Sn-Pb PLATING

10033854- ☐ ☐☐ ☐ ☐ ☐ LF

For Rohs OPTIONS:
TAIL PLATING CODE MUST BE 0~3.
HOLD DOWN PLATING CODE MUST BE "S".
"LF" CODE IS EXIST IN THE END.
EX: 10033854-252TSLF

FOR NOT Rohs COMPATIBLE:
THIS "LF" CODE IS "BLANK".
EX:10033854-452TS

<PACKING METHOD>
R : TAPE REEL
DEFAULT : TRAY
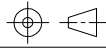
<HOLD DOWN FINISH>
S : Pure Sn
B : Sn-Pb

<CONTACT AREA FINISH>
F : Au FLASH
T : Au 0.3um MIN.
A : Au 0.76um MIN.

<TOTAL HEIGHT>
52 : 5.2mm

<LOCATING PEG, SOLDER TAIL FINISH>
0 : YES, Au FLASH
1 : NO, Au FLASH
2 : YES, Pure Sn PLATING
3 : NO, Pure Sn PLATING
4 : YES, Sn-Pb PLATING
5 : NO, Sn-Pb PLATING

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	FCI www.fciconnect.com
ltr	ecn no	dr	date	linear	.X ± 0.20	projection	title DDR II 0.6 mm PITCH 200 POS. REVERSE TYPE ASS'Y
D					.XX ± 0.10		
				angles	0° ±5°	MM	product family 50UF SO-DIMM code
				dr	M.Hasegawa	6/29/'04	size dwg no JP
				engr	M.Hasegawa	6/29/'04	B 10033854
				chr			scale 2:1
				appd			sheet 4 of
sheet index	revision sheet						

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